DATA SHEET

74ABT16541 74ABTH16541

16-bit buffer/line driver (3-State)

Product specification Supersedes data of 1995 Sep 18 IC23 Data Handbook





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FEATURES

- Power-up 3-State
- Multiple V_{CC} and GND pins minimize switching noise
- Provides ideal interface and increases fan-out of MOS Microprocessors
- 3-State buffers sink 64mA and source 32mA
- 74ABTH16541 incorporates bus-hold data inputs which eliminate the need for external pull-up resistors to hold unused inputs
- Latch-up protection exceeds 500mA per Jedec Std 17
- ESD protection exceeds 2000 V per MIL STD 883 Method 3015 and 200 V per Machine Model
- Two 8-bit bus interfaces
- Bus-hold data inputs eliminate the need for external pull-up resistors to hold unused inputs

DESCRIPTION

The 74ABT16541 high-performance BiCMOS device combines low static and dynamic power dissipation with high speed and high output drive.

The 74ABT16541 has two octal buffers that are ideal for driving bus lines. The outputs are all capable of sinking 64mA and sourcing 32mA.

Two options are available, 74ABT16541 which does not have the bus-hold feature and 74ABTH16541 which incorporates the bus-hold feature.

QUICK REFERENCE DATA

SYMBOL	PARAMETER	CONDITIONS T _{amb} = 25°C; GND = 0V	TYPICAL	UNIT
t _{PLH} t _{PHL}	Propagation delay nAx to nYx	$C_L = 50pF; V_{CC} = 5V$	2.0 1.5	ns
C _{IN}	Input capacitance	$V_I = 0V$ or V_{CC}	4	pF
C _{OUT}	Output capacitance	V _O = 0V or V _{CC} ; 3-State	6	pF
I _{CCZ}	Quippoent gunnly gurrent	Outputs disabled; V _{CC} =5.5V	500	μΑ
Iccl	Quiescent supply current	Outputs LOW; V _{CC} = 5.5V	8	mA

ORDERING INFORMATION

ONDERWING IN ORMANICION				
PACKAGES	TEMPERATURE RANGE	OUTSIDE NORTH AMERICA	NORTH AMERICA	DWG NUMBER
48-Pin Plastic SSOP Type III	-40°C to +85°C	74ABT16541 DL	BT16541 DL	SOT370-1
48-Pin Plastic TSSOP Type II	-40°C to +85°C	74ABT16541 DGG	BT16541 DGG	SOT362-1
48-Pin Plastic SSOP Type III	-40°C to +85°C	74ABTH16541 DL	BH16541 DL	SOT370-1
48-Pin Plastic TSSOP Type II	-40°C to +85°C	74ABTH16541 DGG	BH16541 DGG	SOT362-1

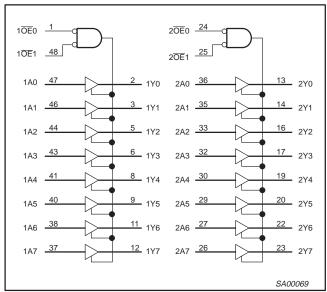
PIN DESCRIPTION

PIN NUMBER	SYMBOL	NAME AND FUNCTION		
47, 46, 44, 43, 41, 40, 38, 37, 36, 35, 33, 32, 30, 29, 27, 26	1A0 - 1A7 2A0 - 2A7	Data inputs		
2, 3, 5, 6, 8, 9, 11, 12, 13, 14, 16, 17 19, 20, 22, 23	1Y0 - 1Y7, 2Y0 - 2Y7	Data outputs		
1, 48 24, 25	1 <u>OE</u> 0, 1 <u>OE</u> 1, 2 <u>OE</u> 0, 2 <u>OE</u> 1	Output enables		
4, 10, 15, 21 28, 34, 39, 45	GND	Ground (0V)		
7, 18, 31, 42	V _{CC}	Positive supply voltage		

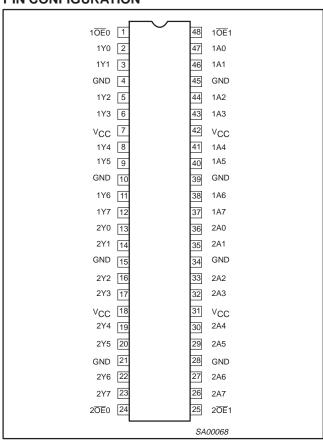
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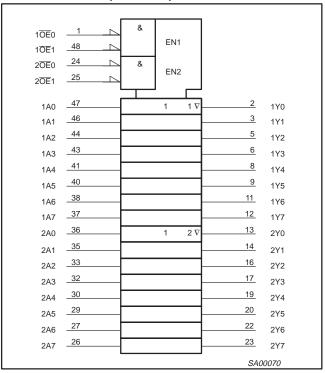
LOGIC SYMBOL



PIN CONFIGURATION



LOGIC SYMBOL (IEEE/IEC)



FUNCTION TABLE

	OUTPUTS		
nOE0	n OE 1	nYx	
L	L	L	L
L	L	Н	Н
X	Н	Х	z
Н	Х	Х	Z

H = HIGH voltage level

_ = LOW voltage level

X = D0n't care

Z = High impedance "off" state

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ABSOLUTE MAXIMUM RATINGS^{1, 2}

SYMBOL	PARAMETER	CONDITIONS	RATING	UNIT
V _{CC}	DC supply voltage		-0.5 to +7.0	V
I _{IK}	DC input diode current	V _I < 0	-18	mA
VI	DC input voltage ³		-1.2 to +7.0	V
I _{OK}	DC output diode current	V _O < 0	-50	mA
V _{OUT}	DC output voltage ³	output in Off or High state	-0.5 to +5.5	V
I _{OUT}	DC output current	output in Low state	128	mA
T _{stg}	Storage temperature range		-65 to 150	°C

NOTES:

- Stresses beyond those listed may cause permanent damage to the device. These are stress ratings only and functional operation of the
 device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to
 absolute-maximum-rated conditions for extended periods may affect device reliability.
- 2. The performance capability of a high-performance integrated circuit in conjunction with its thermal environment can create junction temperatures which are detrimental to reliability. The maximum junction temperature of this integrated circuit should not exceed 150°C.
- 3. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

RECOMMENDED OPERATING CONDITIONS

SYMBOL	PARAMETER	LIM	ITS	UNIT	
STWIBUL	PARAMETER	Min Max			
V _{CC}	DC supply voltage	4.5	5.5	V	
VI	Input voltage	0	V _{CC}	V	
V _{IH}	High-level input voltage	2.0		V	
V _{IL}	Low-level Input voltage		0.8	V	
I _{OH}	High-level output current		-32	mA	
I _{OL}	Low-level output current		64	mA	
Δt/Δν	Input transition rise or fall rate	0	10	ns/V	
T _{amb}	Operating free-air temperature range	-40	+85	°C	

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DC ELECTRICAL CHARACTERISTICS

SYMBOL	PARAMETER	T _a	_{mb} = +25	o°C	T _{amb} = to +	: –40°C 85°C	UNIT		
						Max		Min	Max
V _{IK}	Input clamp voltage	V _{CC} = 4.5V; I _{IK} = -18mA			-0.9	-1.2		-1.2	V
		$V_{CC} = 4.5V; I_{OH} = -3mA; V_{I} = V$	_{IL} or V _{IH}	2.5	2.9		2.5		V
V_{OH}	High-level output voltage	$V_{CC} = 5.0V; I_{OH} = -3mA; V_{I} = V$	_{IL} or V _{IH}	3.0	3.4		3.0		V
		$V_{CC} = 4.5V; I_{OH} = -32mA; V_{I} =$	V _{IL} or V _{IH}	2.0	2.4		2.0		V
V_{OL}	Low-level output voltage	$V_{CC} = 4.5V; I_{OL} = 64mA; V_{I} = V$	_{IL} or V _{IH}		0.42	0.55		0.55	V
I _I	Input leakage current	$V_{CC} = 5.5V$; $V_I = GND \text{ or } 5.5V$			±0.01	±1.0		±1.0	μА
	Input leakage current	$V_{CC} = 5.5V$; $V_I = V_{CC}$ or GND	$V_{CC} = 5.5V$; $V_I = V_{CC}$ or GND Control pins		±0.01	±1		±1	μΑ
I _I	74ABTH16541	$V_{CC} = 5.5V$; $V_I = V_{CC}$	Data pins		0.01	1		1	μΑ
		$V_{CC} = 5.5V; V_I = 0$	Data pins		-2	-3		- 5	μΑ
	Dec Hald come of A Secreta?	$V_{CC} = 4.5V; V_I = 0.8V$	-	50			50		
I _{HOLD}	Bus Hold current A inputs ³ 74ABTH16541	$V_{CC} = 4.5V; V_I = 2.0V$		-75			-75		μΑ
		$V_{CC} = 5.5V$; $V_I = 0$ to 5.5V		±500					
I_{OFF}	Power-off leakage current	$V_{CC} = 0.0V$; V_O or $V_I \le 4.5V$			±5.0	±100		±100	μΑ
I _{PU} /I _{PD}	Power-up/down 3-State output current	$V_{CC} = 2.0V; V_{O} = 0.5V; V_{I} = GN$ $V_{OE} = V_{CC}$	ID or V _{CC} ;		±5.0	±50		±50	μΑ
I _{OZH}	3-State output High current	$V_{CC} = 5.5V$; $V_{O} = 2.7V$; $V_{I} = V_{IL}$	or V _{IH}		1.0	10		10	μΑ
I _{OZL}	3-State output Low current	$V_{CC} = 5.5V; V_{O} = 0.5V; V_{I} = V_{IL}$	or V _{IH}		-1.0	-10		-10	μА
I _{CEX}	Output high leakage current	$V_{CC} = 5.5V; V_{O} = 5.5V; V_{I} = GN$	ID or V _{CC}		1.0	50		50	μА
ΙO	Output current ¹	$V_{CC} = 5.5V; V_{O} = 2.5V$		-50	-70	-180	-50	-180	mA
I _{CCH}		$V_{CC} = 5.5V$; Outputs High, $V_{I} =$	GND or V _{CC}		0.5	1.0		1.0	mA
I _{CCL}	Quiescent supply current	$V_{CC} = 5.5V$; Outputs Low, $V_I = 0$	GND or V _{CC}		8	19		19	mA
I _{CCZ}		V_{CC} = 5.5V; Outputs 3-State; V_{I} = GND or V_{CC}		0.5	1.0		1.0	mA	
Δl _{CC}	Additional supply current per input pin ² 74ABT16541	Outputs enabled, one input at 3 inputs at V _{CC} or GND; V _{CC} = 5.			100	250		250	μА
ΔI_{CC}	Additional supply current per input pin ² 74ABTH16541	Outputs enabled, one input at 3 inputs at V _{CC} or GND; V _{CC} = 5.	.4V, other 5V		0.2	1.0		1.0	mA

NOTES:

- Not more than one output should be tested at a time, and the duration of the test should not exceed one second.
 This is the increase in supply current for each input at 3.4V.
- 3. This is the bus hold overdrive current required to force the input to the opposite logic state.

AC CHARACTERISTICS

GND = 0V; t_R = t_F = 2.5ns; C_L = 50pF, R_L = 500 Ω

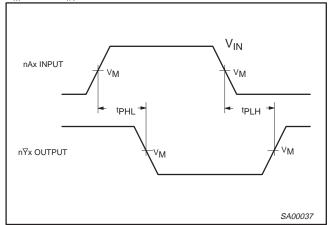
SYMBOL PARAMETER		WAVEFORM	T _z	_{amb} = +25° CC = +5.0°	C V	T _{amb} = -40° V _{CC} = +5.	UNIT	
			Min	Тур	Max	Min	Max	
t _{PLH} t _{PHL}	Propagation delay nlx to nYx	1	1.0 1.0	2.0 1.5	3.0 3.6	1.0 1.0	3.4 4.2	ns
t _{PZH} t _{PZL}	Output enable time to High and Low level	2	1.3 1.6	2.9 3.1	4.3 4.7	1.3 1.6	5.2 6.0	ns
t _{PHZ} t _{PLZ}	Output disable time from High and Low level	2	1.3 1.0	3.5 2.8	4.4 3.6	1.3 1.0	5.1 3.9	ns

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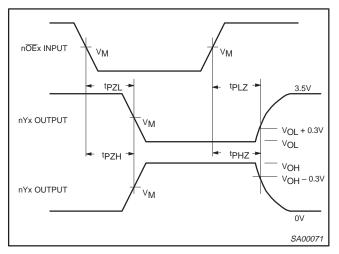
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AC WAVEFORMS

 $V_{M} = 1.5V, V_{IN} = GND \text{ to } 3.0V$

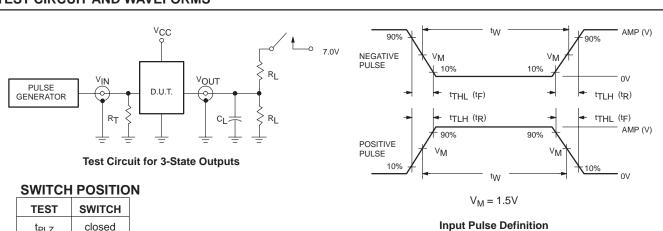


Waveform 1. Input (An) to Output (Yn) Propagation Delays



Waveform 2. 3-State Output Enable and Disable Times

TEST CIRCUIT AND WAVEFORMS



TEST	SWITCH
t _{PLZ}	closed
t _{PZL}	closed
All other	open

DEFINITIONS

 R_L = Load resistor; see AC CHARACTERISTICS for value.

 $C_L = Load$ capacitance includes jig and probe capacitance; see AC CHARACTERISTICS for value.

 $R_T = Termination resistance should be equal to <math>Z_{OUT}$ of pulse generators.

FAMILY	INPUT PULSE REQUIREMENTS								
FAMILI	Amplitude	Rep. Rate	t _W	t _R	t _F				
74ABT	3.0V	1MHz	500ns	2.5ns	2.5ns				

SA00012

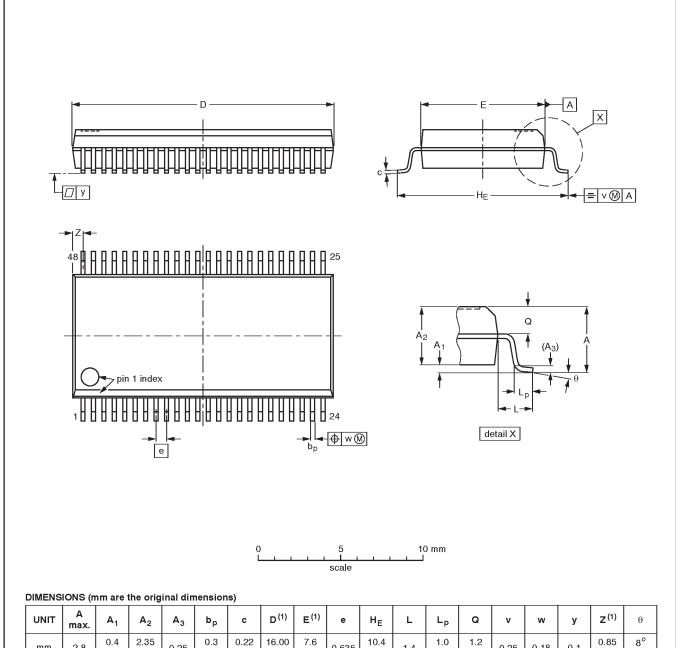
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16-bit buffer/line driver (3-State)

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SSOP48: plastic shrink small outline package; 48 leads; body width 7.5 mm

SOT370-1



l	TINU	A max.	A ₁	A ₂	A ₃	bp	c	D ⁽¹⁾	E ⁽¹⁾	е	HE	L	Lp	Q	v	w	у	Z ⁽¹⁾	θ
	mm	2.8	0.4 0.2	2.35 2.20	0.25	0.3 0.2	0.22 0.13	16.00 15.75	7.6 7.4	0.635	10.4 10.1	1.4	1.0 0.6	1.2 1.0	0.25	0.18	0.1	0.85 0.40	8° 0°

Note

1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

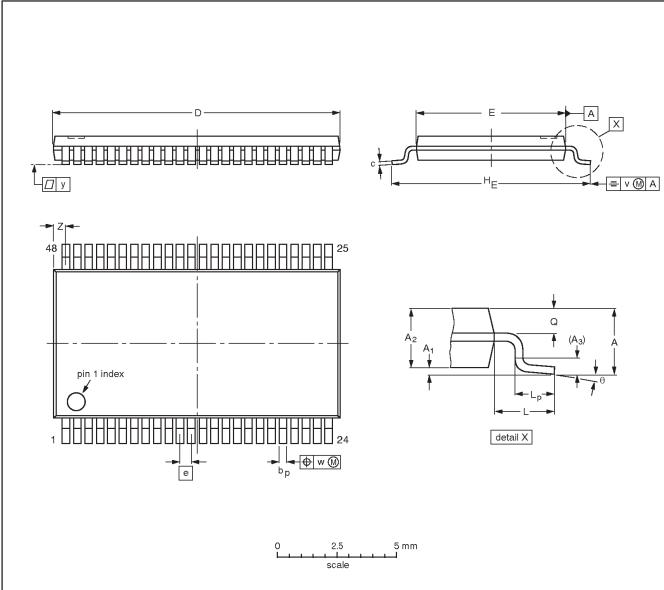
OUTLINE		REFER	EUROPEAN	ISSUE DATE		
VERSION	IEC	JEDEC	EIAJ		PROJECTION	ISSUE DATE
SOT370-1		MO-118AA				93-11-02 95-02-04

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TSSOP48: plastic thin shrink small outline package; 48 leads; body width 6.1mm

SOT362-1



DIMENSIONS (mm are the original dimensions).

UNIT	A max.	A ₁	A ₂	A ₃	bp	С	D ⁽¹⁾	E ⁽²⁾	е	HE	L	Lp	Q	v	w	у	z	θ
mm	1.2	0.15 0.05	1.05 0.85	0.25	0.28 0.17	0.2 0.1	12.6 12.4	6.2 6.0	0.5	8.3 7.9	1	0.8 0.4	0.50 0.35	0.25	0.08	0.1	0.8 0.4	8° 0°

Notes

- 1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.
- 2. Plastic interlead protrusions of 0.25 mm maximum per side are not included.

OUTLINE		REFER	EUROPEAN	ISSUE DATE		
VERSION	IEC	JEDEC	EIAJ		PROJECTION	ISSUE DATE
SOT362-1		MO-153ED				-93-02-03- 95-02-10

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NOTES

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Data sheet status

Data sheet status	Product status	Definition [1]
Objective specification	Development	This data sheet contains the design target or goal specifications for product development. Specification may change in any manner without notice.
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^[1] Please consult the most recently issued datasheet before initiating or completing a design.

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Limiting values definition — Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.

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print code Date of release: 05-96

Document order number: 9397-750-03495

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